



BGA
CSP
MCM

(Micro Screen is option)

Simple Ball Mounting Device SP-100BR

The SP-100BR with MICRO SCREEN (μ S-100 series, option) is a machine for mounting ball terminals on BGA, CSP, MCM and other packages. Its applicability ranges from CSP with 48 pins to MCM with 1,500 pins for balls with a diameter of 0.4mm \varnothing to 0.89mm \varnothing . With the machine it is easy to mount ball terminals on a small quantity of packages when re-balling on reprocessed packages, or when mounting balls on chips which are under development etc.

Features

- * Application range from CSP with 48 pins to BGA and MCM with 1,500 pins for balls with a diameter of 0.4mm to 0.89mm. (MICRO SCREEN is optional)
- * Flux/cream solder printing and ball aligning are possible with this single machine. (Both the screen for cream printing and the screen for ball aligning these devices are necessary.)
- * The screen position (X, Y, Z) can be fine-adjusted with 10 μ m accuracy based on the micro meter.
- * It is possible to carry out reflow-soldering immediately after ball alignment; a manual-type N₂ reflow machine RF-110N2 is also available. (Reflow jig for high temperature (290°C) solder ball can be also arranged for.)

Specifications

- μ S-100series(option)
 - Size : From 14x28mm to 54x63mm (7 types)
 - Thickness : 0.15mm (CSP 0.13mm)
 - Material : Frame SPCC
Screen SUS304
- Fine-adjustment of X, Y, Z : 15mm (10 μ m steps)
- Dimensions/Mass
 - Main unit (W)250x(L)450x(H)160mm 8kg
 - Control box (W)180x(D)250x(H)110mm 3kg

Applicable package

- Size : From 6x6 to 50x50mm
- Number of pins : From 48 to 1,500 pins
- Pitch : 1.5mm to 0.5mm
- Ball diameter : 0.89mm \varnothing to 0.4mm \varnothing
- Soldering ball : 183°C, 290°C

Options

- Micro Screen μ S-100series
- Manual reflow soldering equipment RF-110
RF-110N2
- Chip adsorption Stage Special order

Also please refer to the μ S-100series Catalogue.

* Specifications subject to change without notice.